

CMOS

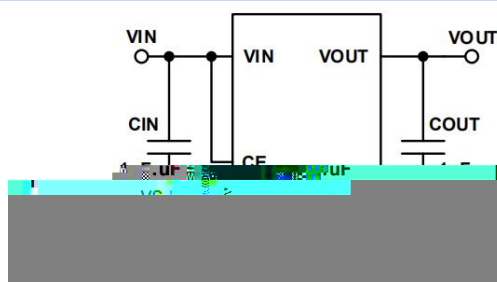
特征 / Features

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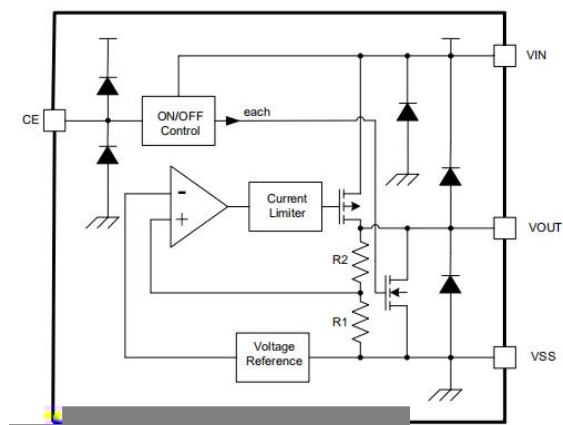
用途 / Applications

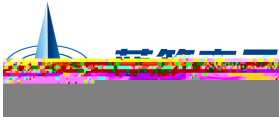
◆◆◆◆◆

典型应用电路图 / Typical Application

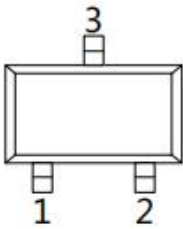


功能框图 / Functional Block Diagram

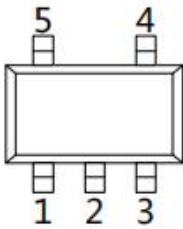




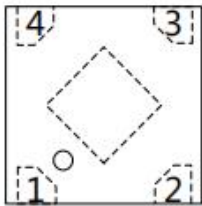
引脚排列 / Pinning



SOT23-3



SOT23-5



DFN1*1-4L



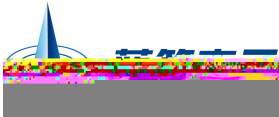
SOT23-3	SOT23-5	DFN1*1-4L	SOT-89		
1	2	2	1	VSS	
3	1	4	2	VIN	
2	5	1	3	VOUT	
-	3	3	-	CE	
-	4	-	-	NC	

型号 / Part Number

① ②							
①	MC SOT23-3 ME SOT23-5 TA SOT-89 ZN DFN1*1-4L						
②	1.2 1.2V						

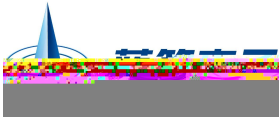
极限参数 / Absolute Maximum Ratings(Ta=25°C)

		()	
		()	
		()	
		()	
			℃

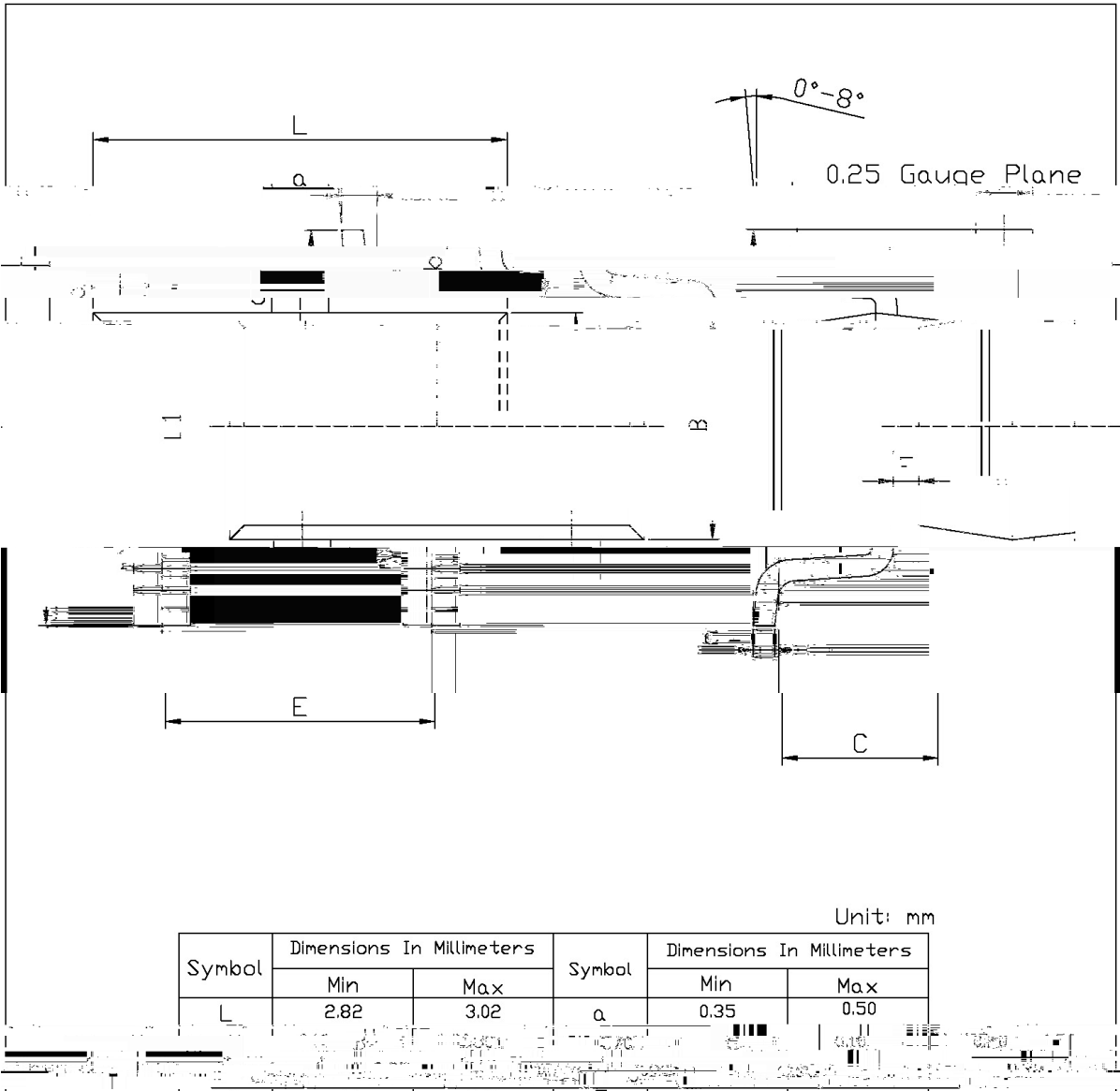


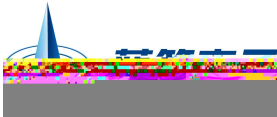
参数	符号	测试条件	最小值	典型值	最大值	单位
输入电压						
输出电压 ()	()					



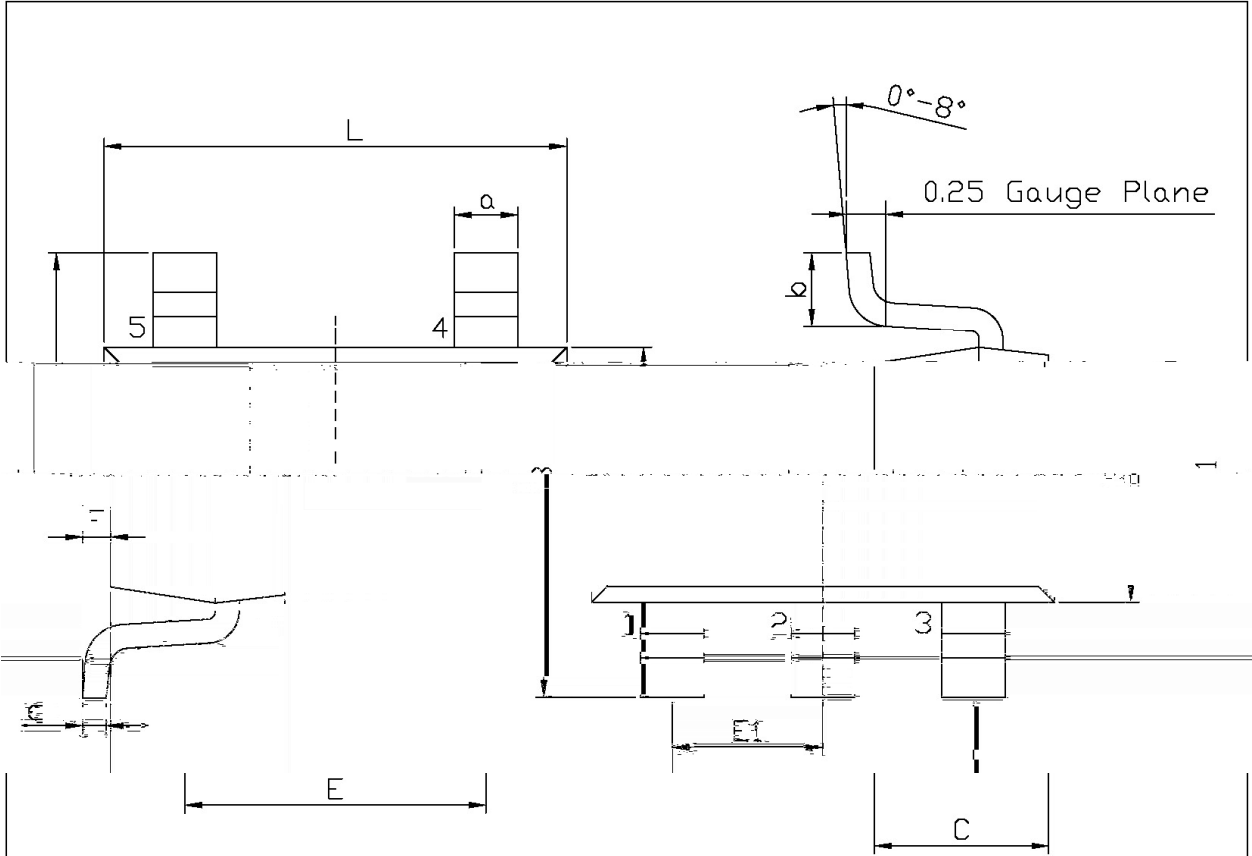


外形尺寸图 / Package Dimensions



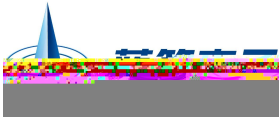


外形尺寸图 / Package Dimensions



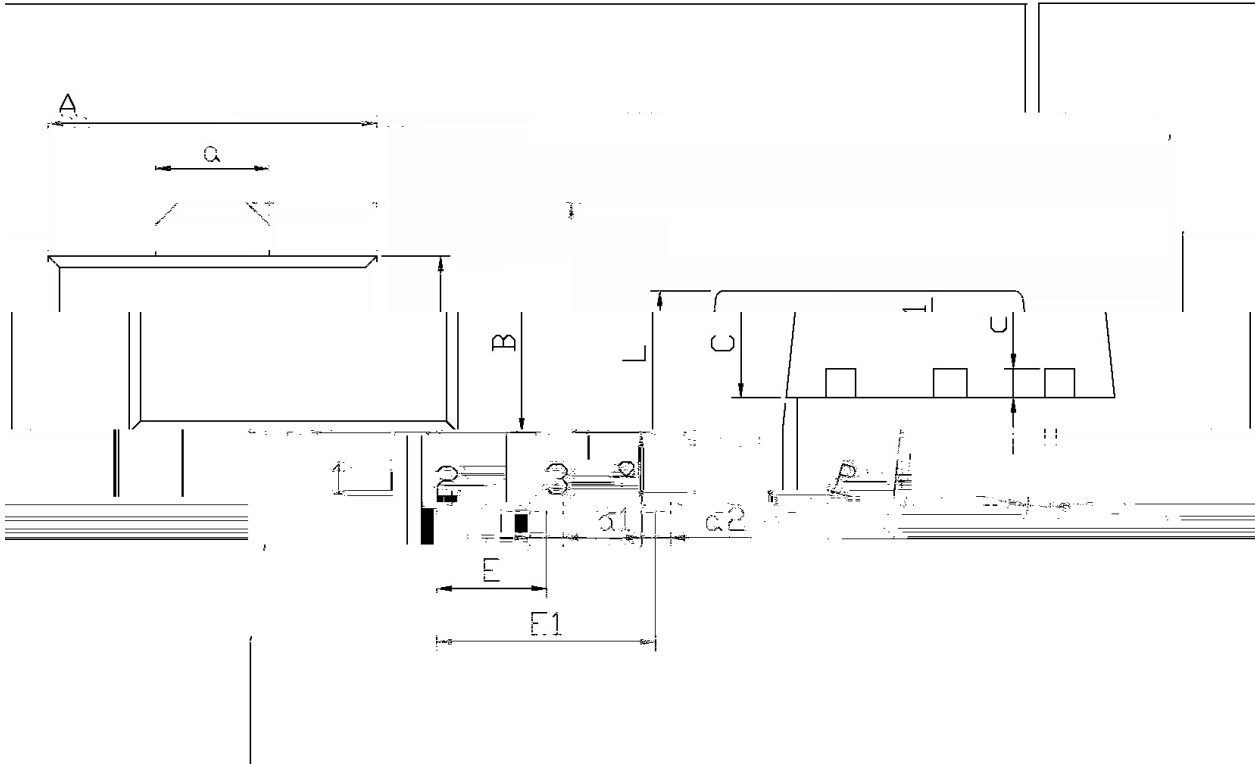
Unit: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
1	0.25	0.35	2	0.25	0.35
3	0.25	0.35	4	0.25	0.35
5	0.25	0.35	6	0.25	0.35

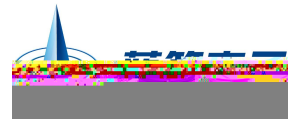


外形尺寸图 / Package Dimensions

单位: mm



Dimensions in Millimeters			Dimensions in Inches		
Symbol	Min	Max	Symbol	Min	Max
A	4.41	4.57	a1	0.36	0.50
B	3.35	3.65	a2	1.20	1.50
C	0.878	0.978	L	0.50	1.40
E	1.40	1.50			
E1	2.80	3.20			
	0.89	1.20			

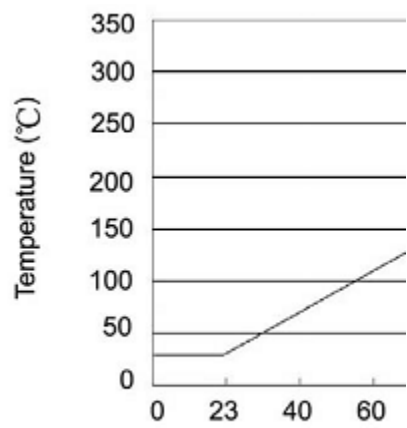


BRCO2600Series



BRCO2600Series

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(



耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

包装规格 / Packaging SPEC.

封装形式	Units/Reel	Reels/Inner Box	Ur
	只/卷盘	卷盘/盒	
SOT23-3/5	3,000	10	

封装形式	Units/Reel	Reels/Inner Box	U
	只/卷盘	卷盘/盒	
SOT-89	1,000	7	

Package Type	Units/Reel	Reels/Inner Box	Uni
	只/卷盘	卷盘/盒	
DFN1*1-4L/6L	10,000	10	1

使用说明 / Notices